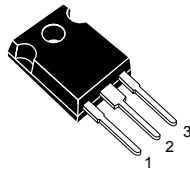
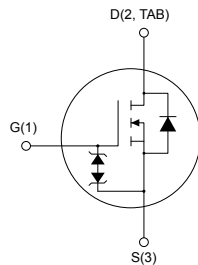


# N-channel 600 V, 61 mΩ typ., 39 A, MDmesh™ M6 Power MOSFET in a TO-247 package


**TO-247**


AM01475V1


**Product status link**
[STW48N60M6](#)
**Product summary**

<b>Order code</b>	STW48N60M6
<b>Marking</b>	48N60M6
<b>Package</b>	TO-247
<b>Packing</b>	Tube

## Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STW48N60M6	600 V	69 mΩ	39 A

- Reduced switching losses
- Lower R<sub>DS(on)</sub> per area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications
- LLC converters
- Boost PFC converters

## Description

The new MDmesh™ M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs. STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent R<sub>DS(on)</sub> per area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum end-application efficiency.

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	39	A
	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	25	A
$I_{DM}^{(1)}$	Drain current (pulsed)	140	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	100	
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2.  $I_{SD} \leq 39\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ,  $V_{DS(peak)} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$
3.  $V_{DS} \leq 480\text{ V}$

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.5	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )	5.5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	950	mJ

## 2 Electrical characteristics

( $T_C = 25\text{ }^\circ\text{C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	600			V
$I_{DSS}$	Zero-gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}, T_C = 125\text{ }^\circ\text{C}^{(1)}$			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.25	4	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 19.5\text{ A}$		61	69	$\text{m}\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 100\text{ V}, f = 1\text{ MHz}$	-	2578	-	$\text{pF}$
$C_{oss}$	Output capacitance		-	202	-	$\text{pF}$
$C_{rss}$	Reverse transfer capacitance		-	3.1	-	$\text{pF}$
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ to }480\text{ V}$	-	415	-	$\text{pF}$
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	1.8	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480\text{ V}, I_D = 39\text{ A}, V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	57	-	$\text{nC}$
$Q_{gs}$	Gate-source charge		-	16	-	$\text{nC}$
$Q_{gd}$	Gate-drain charge		-	23	-	$\text{nC}$

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}, I_D = 19.5\text{ A}, R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	28	-	ns
$t_r$	Rise time		-	34	-	ns
$t_{d(off)}$	Turn-off delay time		-	60	-	ns
$t_f$	Fall time		-	9.5	-	ns

**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		39	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		140	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 39\text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 39\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	317		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	4.4		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	28		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 39\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	475		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$	-	8.67		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	36.5		A

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

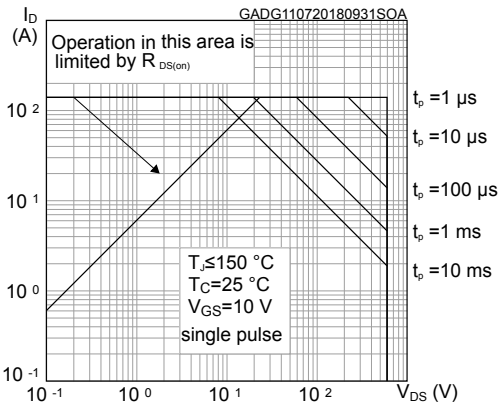


Figure 2. Thermal impedance

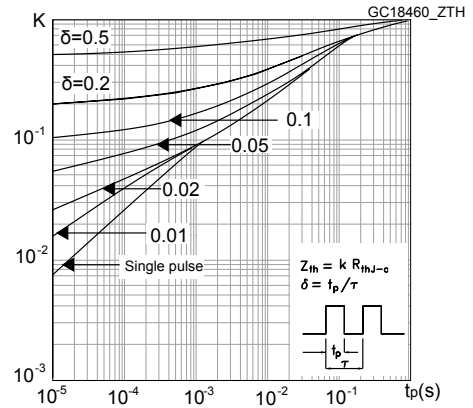


Figure 3. Output characteristics

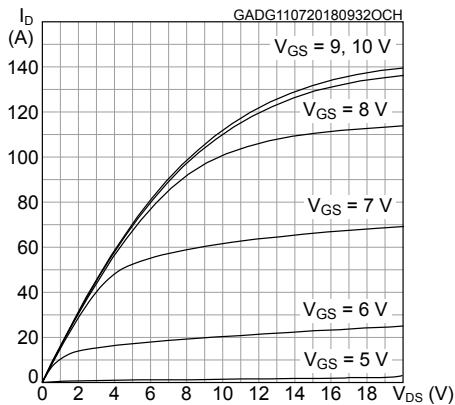


Figure 4. Transfer characteristics

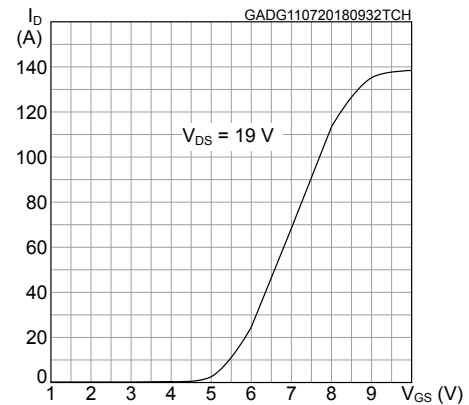


Figure 5. Gate charge vs gate-source voltage

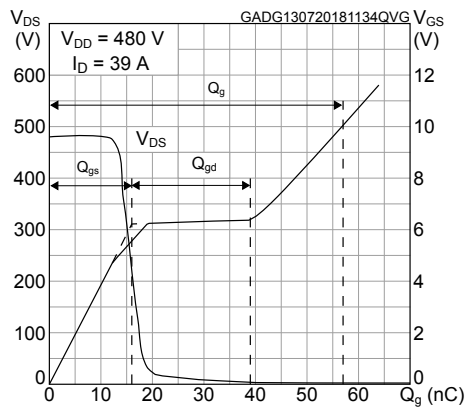


Figure 6. Static drain-source on-resistance

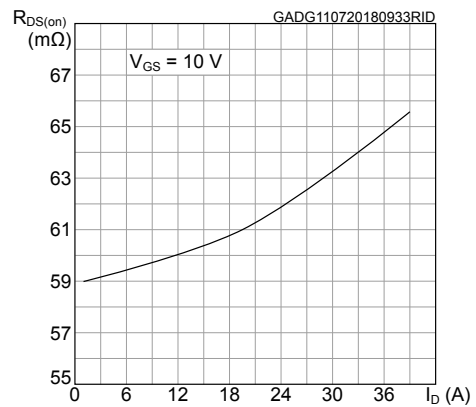


Figure 7. Capacitance variations

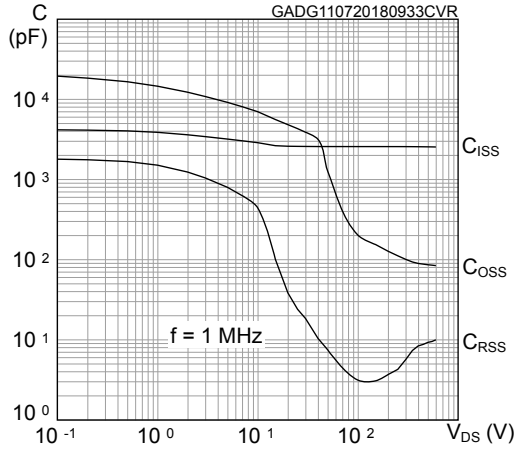


Figure 8. Normalized gate threshold voltage vs temperature

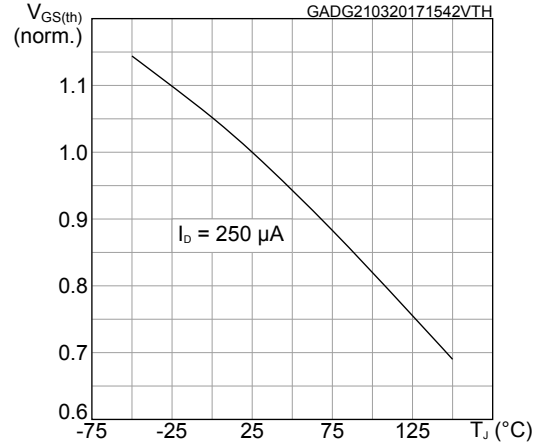


Figure 9. Normalized on-resistance vs temperature

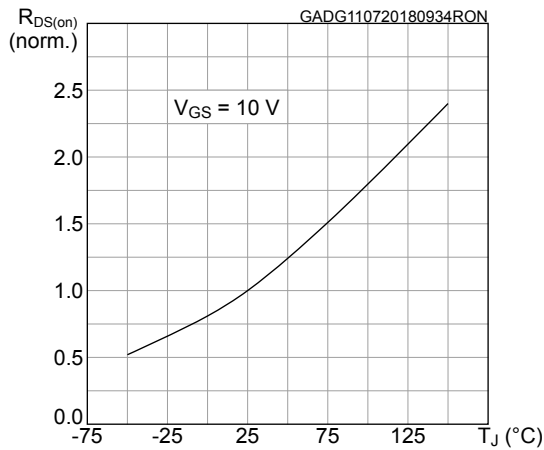


Figure 10. Normalized  $V_{(BR)DSS}$  vs temperature

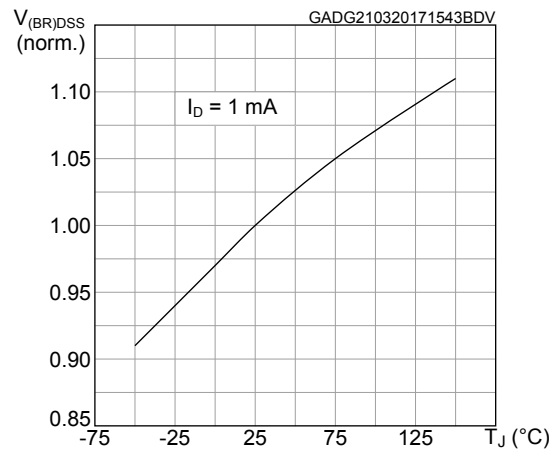


Figure 11. Output capacitance stored energy

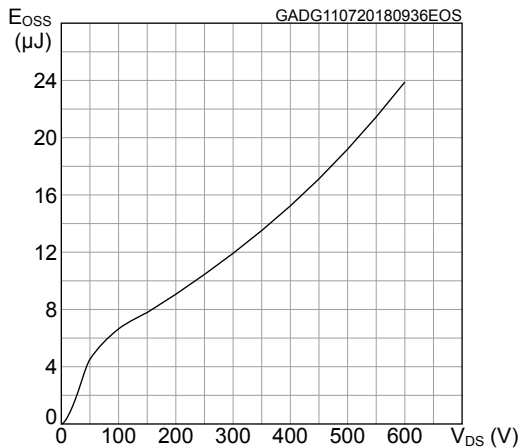
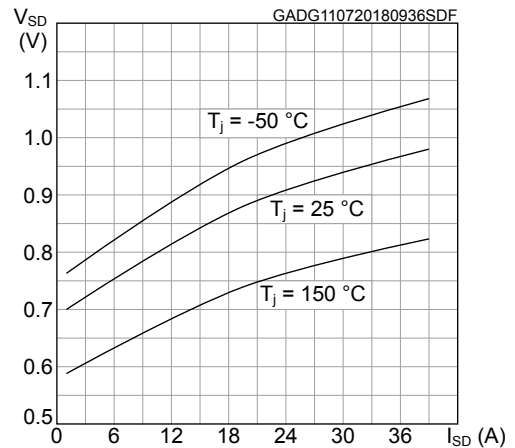
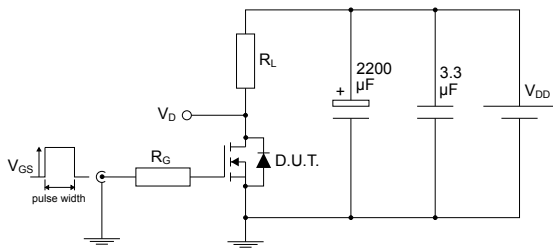


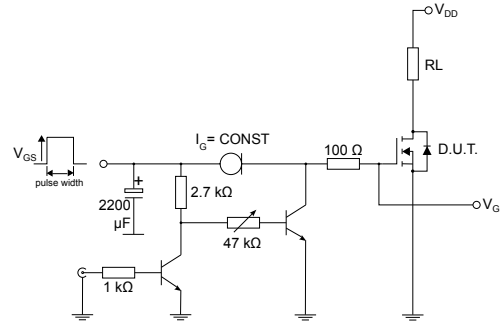
Figure 12. Source-drain diode forward characteristics



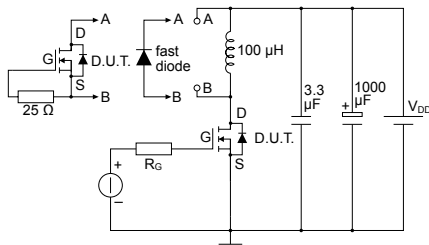
### 3 Test circuits

**Figure 13. Test circuit for resistive load switching times**


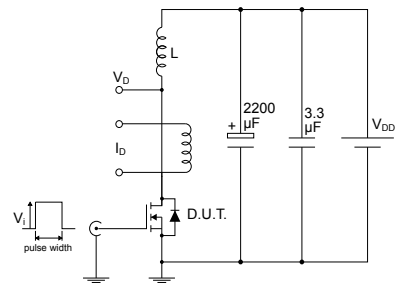
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**Figure 14. Test circuit for gate charge behavior**


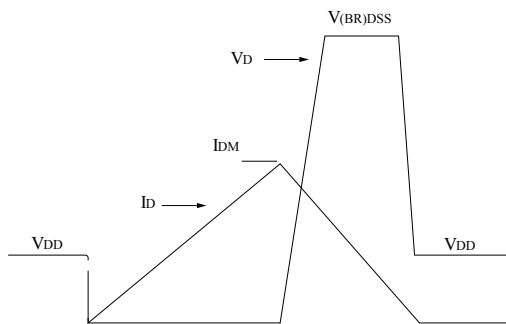
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**Figure 15. Test circuit for inductive load switching and diode recovery times**


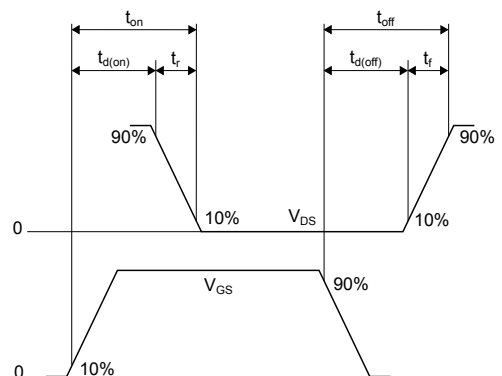
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**Figure 16. Unclamped inductive load test circuit**


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**Figure 17. Unclamped inductive waveform**


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**Figure 18. Switching time waveform**


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## 4 Package information

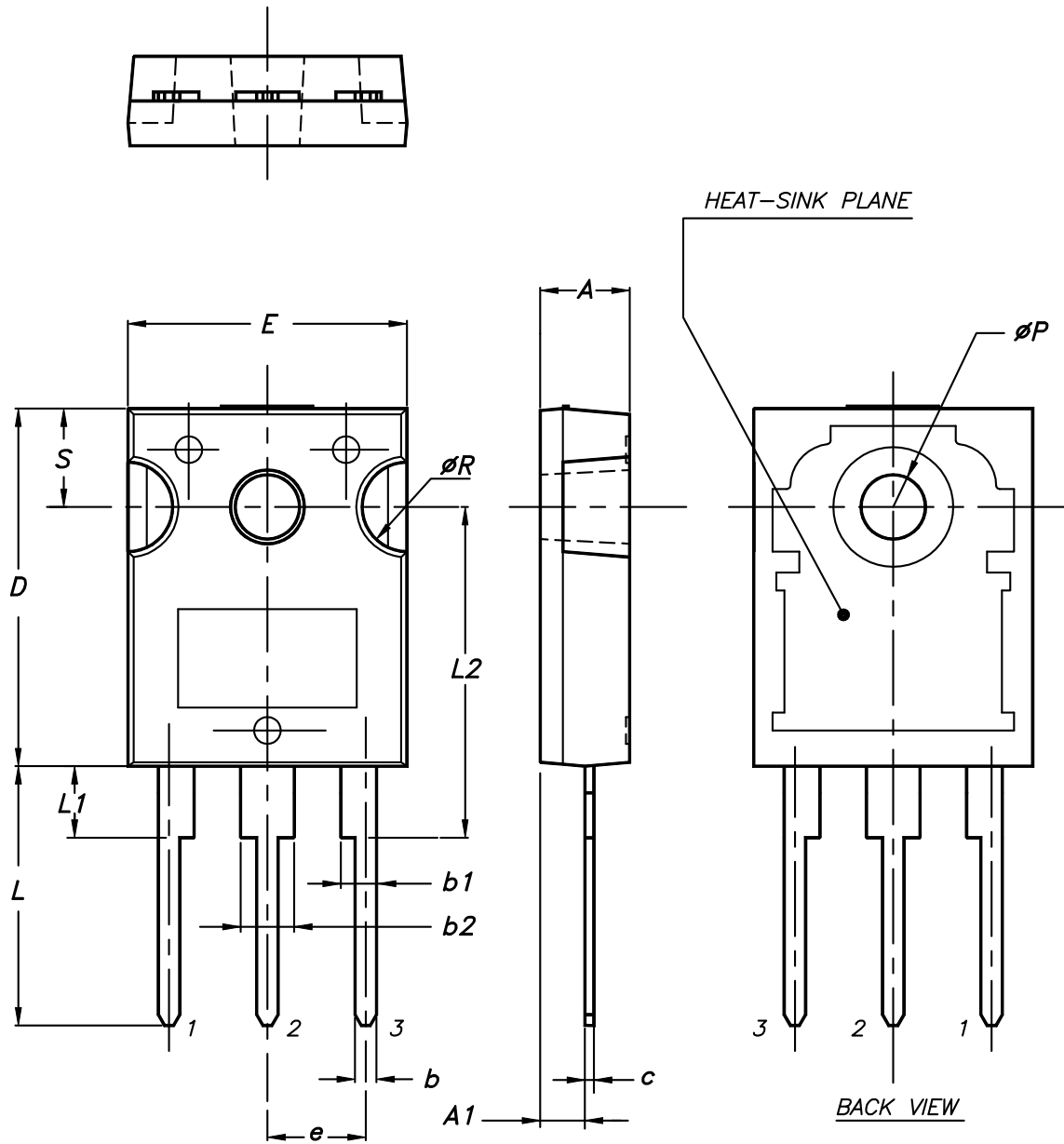
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In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.



### 4.1 TO-247 package information

Figure 19. TO-247 package outline



0075325\_9

**Table 8. TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

## Revision history

**Table 9. Document revision history**

Date	Version	Changes
25-Jul-2018	1	Initial release.
25-Oct-2018	2	Modified Table 1. Absolute maximum ratings, Table 4. On/off states and Table 5. Dynamic. Modified Figure 1. Safe operating area, Figure 5. Gate charge vs gate-source voltage, Figure 6. Static drain-source on-resistance, Figure 9. Normalized on-resistance vs temperature, Figure 10. Normalized $V_{(BR)DSS}$ vs temperature and Figure 12. Source-drain diode forward characteristics. Minor text changes.

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